TVS Diode Datasheet



EFT protection of data lines in

accordance with IEC 61000-

Fast response time: typically

 High temperature soldering: 260°C/30 seconds at

Meet MSL level1, per J-STD-

020C, LF maximun peak of

Matte tin lead-free plated

Pb-free E3 means 2nd level

interconnect is Pb-free and

tin(Sn) (IPC/JEDEC J-STD-

the terminal finish material is

Halogen-free and RoHS-

less than 1.0ns from 0 Volts



Additional Information



Agency Approvals

Agency	Agency File Number
91	E230531

Maximum Ratings and Thermal Characteristics $(T_a=25 \ ^{\circ}C \text{ unless otherwise noted})$

Parameter	Symbol	Value	Unit	
Peak Pulse Power Dissipation at	8/20µs (Note 2)	D	2000	W
$T_A = 25^{\circ}C$ (Note 1)	10/1000µs (Note 3)	P _{PPM}	400	W
Thermal Resistance	$R_{_{\thetaJA}}$	220	°C/W	
Thermal Resistance	$R_{_{ ext{ hetaJL}}}$	100	°C/W	
Operating Tempera	TJ	-55 to 150	°C	
Storage Temperatur	T _{stg}	-55 to 150	°C	

Notes:

1. Non-repetitive current pulse, per Fig. 4 and derated above T_J (initial) =25°C per Fig. 3.

Description

SMF3.3 is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

4-4

to VBR min

terminals

260°C

compliant

609A.01)

Built-in strain relief

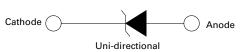
Features

- 200W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycle): 0.01%
- 1200W peak pulse power capability at 8/20us waveform
- Excellent clamping capability
- Compatible with industrial standard package SOD-123FL
- Low profile: maximum height of 1.1mm.
- For surface mounted applications to optimize board space
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC 61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2

Applications

SMF3.3 devices are ideal for the protection of portable devices/ hard drives, notebooks, VCC busses, POS terminal, SSDs, power supplies, monitors, and vulnerable circuit used in other consumer applications.

Functional Diagram



Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Number	Marking Code		down geV _{BR} ;) @ I _T MAX	Test Current I _T (mA)	Reverse Stand off Voltage V _R (V)	Maximum Reverse Leakage @ V _R Ι _R (μΑ)	Maximum Peak Pulse Current (10/1000µS) I _{pp} (A)	Maximum Clamping Voltage @l _{pp} (10/1000µS) V _c (V)	Maximum Peak Pulse Current (8/20µS) I _{pp} (A)	Maximum Clamping Voltage @l _{pp} (8/20μS) V _c (V)
SMF3.3	33	3.4	4.3	10	3.3	0.5	30.0	6.8	120.0	10.0

Notes

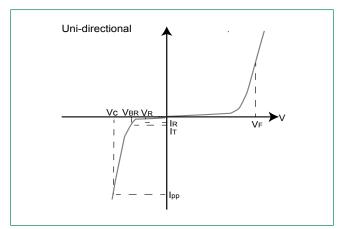
1. V_{BR} measured after I_T applied for 300µs, I_T = sequare wave pulse or equivalent.

Surge current waveform per 10/1000µs exponential wave and derated per Fig.2.
All terms and symbols are consistent with ANSI/IEEE C62.35.

Surge current waveform per 8/20µs exponential wave and derated per Fig.6.



I-V Curve Characteristics



- P_{PPM} Peak Pulse Power Dissipation Max power dissipation
- $\mathbf{V}_{_{\!R}}$ Stand-off Voltage -- Maximum voltage that can be applied to the TVS without operation
- V_{BR} Breakdown Voltage Maximum voltage that flows though the TVS at a specified test current (IT)
- V_c Clamping Voltage Peak voltage measured across the TVS at a specified lppm (peak impulse current)
- I_R Reverse Leakage Current -- Current measured at VR
- V_F Forward Voltage Drop for Uni-directional

Note: VF distribution range from 7V to 16V at IF 1mA.

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

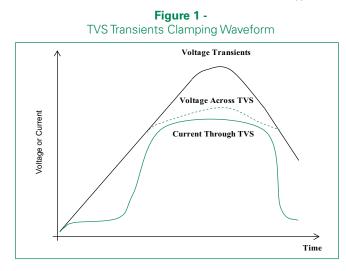
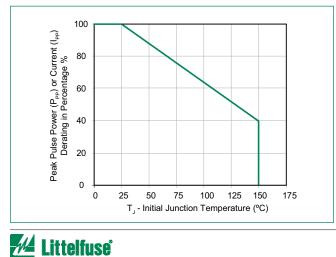
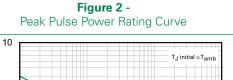


Figure 3 -Peak Pulse Power Derating Curve





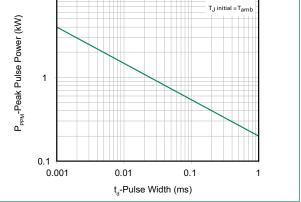
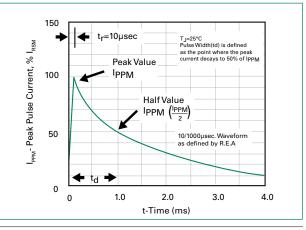
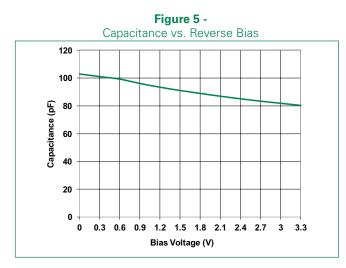


Figure 4 -10/1000µS Pulse Waveform



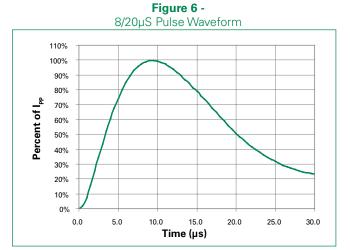


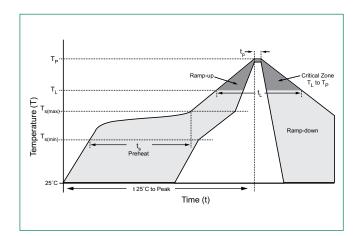
Soldering Parameters

Reflow Cond	lition	Lead–free assembly	
	- Temperature Min (T _{s(min)})	150°C	
Pre Heat	- Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 - 120 secs	
Average ram peak	p up rate (Liquidus Temp (\mathbf{T}_{L}) to	3°C/second max	
$T_{S(max)}$ to T_{L} - I	Ramp-up Rate	3°C/second max	
Reflow	- Temperature (T _L) (Liquidus)	217°C	
nellow	-Time (min to max) (t _L)	60 – 150 seconds	
Peak Temper	ature (T _P)	260 ^{+0/-5} °C	
Time within	5°C of actual peak Temperature (t _p)	30 seconds max	
Ramp-down	Rate	6°C/second max	
Time 25°C to	peak Temperature (T _P)	8 minutes max.	
Do not excee	ed	260°C	



Case	SOD-123FL plastic over passivated junction
Polarity	Color band denotes cathode except bipolar
Terminal	Matte tin-plated leads, solderable per JESD22-B102



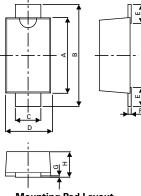


Environmental Specification

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, LEVEL 1
H3TRB	JESD22-A101
RSH	JESD22-A111

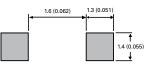


Dimensions - SOD-123FL Package

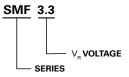


Dimensions	Millin	neters	Inches		
Dimensions	Min	Max	Min	Max	
A	2.90	3.10	0.114	0.122	
В	3.50	3.90	0.138	0.154	
С	0.85	1.05	0.033	0.041	
D	1.70	2.00	0.067	0.079	
E	0.43	0.83	0.017	0.033	
F	0.10	0.25	0.004	0.010	
G	0.00	0.10	0.000	0.004	
Н	0.90	1.08	0.035	0.043	

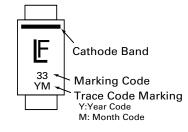
Mounting Pad Layout



Part Numbering System

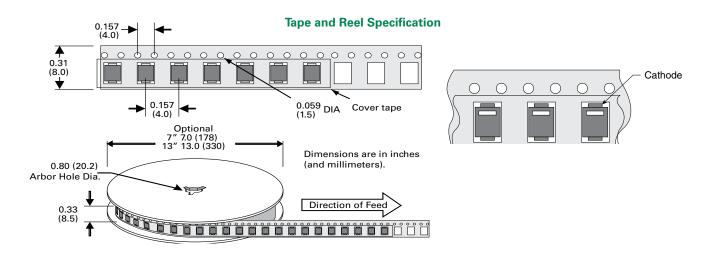


Part Marking System



Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMF3.3	SOD-123FL	3000	Tape & Reel – 8mm tape/7" reel	EIA RS-481



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